

Title (en)

High-modulus iron-based alloy and a process for manufacturing the same.

Title (de)

Legierung auf Stahlbasis mit hohem Modul und Verfahren zu deren Herstellung.

Title (fr)

Aciers à modules élevés et procédé de leur fabrication.

Publication

EP 0659894 A3 19951115 (EN)

Application

EP 94120574 A 19941223

Priority

- JP 35446793 A 19931227
- JP 6759094 A 19940311

Abstract (en)

[origin: EP0659894A2] A high-modulus iron-based alloy containing at least one boride dispersed in an iron or iron-alloy matrix. The boride may be one of a Group IVa element, or a complex boride of at least one Group Va element and iron. A mixture of an iron or iron-alloy powder and a powder of at least one boride containing a Group IVa or Va element is compacted and sintered to make a shaped high-modulus iron-based alloy product.

IPC 1-7

C22C 38/00

IPC 8 full level

C22C 33/02 (2006.01)

CPC (source: EP US)

C22C 33/0292 (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

EP 0659894 A2 19950628; EP 0659894 A3 19951115; EP 0659894 B1 20050504; DE 69434357 D1 20050609; DE 69434357 T2 20060309; US 5854434 A 19981229

DOCDB simple family (application)

EP 94120574 A 19941223; DE 69434357 T 19941223; US 78508797 A 19970121